

Observation of the Mott Transition in VO₂ Based Transistors

Hyun-Tak Kim*, B. G. Chae, D. H. Youn, S. L. Maeng, K. Y. Kang
Telecom. Basic Research Lab., ETRI, Daejeon 305-350, South Korea
(August 2, 2003)

An abrupt Mott metal-insulator transition (MIT) rather than the continuous Hubbard MIT near a critical on-site Coulomb energy $U/U_c=1$ is observed for the first time in VO₂, a strongly correlated material, by inducing holes of about 0.018% into the conduction band. As a result, a discontinuous jump of the density of states on the Fermi surface is observed and inhomogeneity inevitably occurs. The gate effect in fabricated transistors is clear evidence that the abrupt MIT is induced by the excitation of holes.

PACS numbers: 71.27.+a, 71.30.+h

In a strongly correlated system, a metal-insulator transition (MIT) near a critical on-site Coulomb energy, $U/U_c=1$, has long been controversial in terms of whether the transition is abrupt or continuous in experiments [1-4], although a first-order MIT with temperature was observed by Morin [5]. An abrupt MIT indicates the Mott transition (first order) and a continuous MIT is the Hubbard transition (second order). The MIT breaks down an energy gap, formed by the strongly correlated Coulomb energy, between sub-bands in a main band. Mott first predicted that the abrupt MIT occurs when a lattice constant is larger than a critical value [1]. Brinkman and Rice theoretically demonstrated an abrupt MIT near $U/U_c=1$ for a strongly correlated metal with an electronic structure of one electron per atom [6]. Hubbard first derived that, when sub-bands overlap just below U_c , there is a finite minimum density of states (DOS) at the Fermi level, the DOS increases with decreasing U , and the system is metallic [7]; this is Hubbard's continuous MIT. Later, the continuous MIT was confirmed in the infinite-dimensional Hubbard model [2].

Applying an electric field to a two-terminal structure, Kumai *et al.* [8] measured Ohmic behavior in an organic Mott insulator in a regime, where conduction from non-conduction (insulating behavior) occurs. Through a theoretical consideration based on the Hubbard model, Oka *et al.* [9] described the Ohmic behavior in terms of a universal Landau-Zener quantum tunneling. Boriskov *et al.* [10] also observed a similar metallic behavior for VO₂ to that measured by Kumai *et al.* [8]. Thus, on the basis of the metallic behaviors and Oka's analysis, the MIT just below U_c seems to follow Hubbard's continuous model. However, considering the abrupt MIT observed in resistance measurement (Fig. 1), an abrupt MIT in the electric field should also be found.

In this letter, we observe an abrupt jump of current (or DOS) at an electric field in a two-terminal structure and measure the gate effect of the jump in a three-terminal device (switching transistor). The abrupt jump is analyzed in terms of an abrupt MIT (Mott transition). Inducing internal hole charges of about 0.018% in hole levels into the conduction band with a source-drain field or a gate field of a fabricated transistor [11] is an ef-

fective method of revealing the MIT mechanism. Note that Mott criterion, $n_c \approx 3 \times 10^{18} \text{ cm}^{-3}$, is obtained from $n_c^{1/3} a_H \approx 0.25$, where a_H is the Bohr radius for VO₂ [12]. n_c corresponds to about 0.018% of the number of carriers in the half-filled band, when one electron in the cell volume, $59.22 \times 10^{-24} \text{ cm}^3$, of VO₂ is assumed; the number of electrons is about $1.7 \times 10^{22} \text{ cm}^{-2}$.

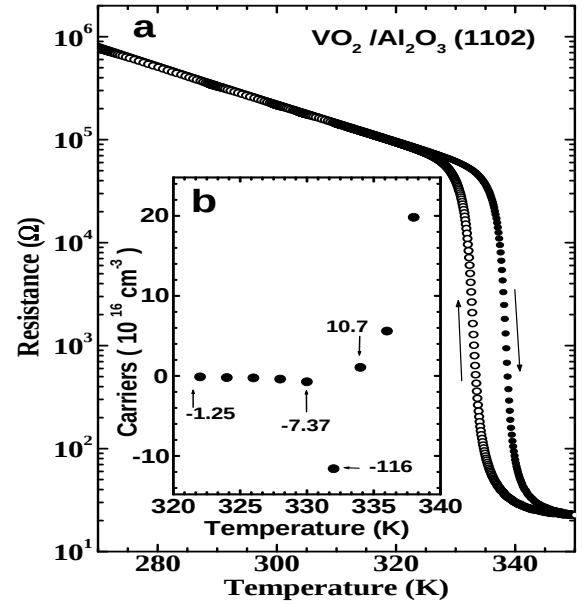


FIG. 1. **a**, Temperature dependence of the resistance of a VO₂ film. Hysteresis is shown. **b**, The number of carriers measured by Hall effect. A change of carriers from holes to electrons is shown at 332 K. The minus sign indicates that the carriers are holes.

Thin films of a Mott insulator, VO₂, with a sub-energy gap of about 1 eV in the *d* band [13,14], have been deposited on Al₂O₃ and Si substrates by laser ablation. The thickness of the VO₂ films is about 900 Å. The resistance of the film decreases with increasing temperature and shows an abrupt MIT at a transition temperature, $T_{tr}=340 \text{ K}$ (68°C) (Fig. 1a). This corresponds with that measured by De Natale *et al.* [15] and Borek *et al.* [16].

It was proposed that the abrupt MIT is the structural phase transition from monoclinic below T_{tr} to tetragonal above T_{tr} [5]. The decrease of the resistance up to 340 K indicates an increase of hole carriers, and two kinds of electron and hole carriers coexist near $T_{tr}=340$ K (Fig. 1b). From 332 to 340 K, the number of carriers is not discernable because of mixing of electrons and holes. We speculate that the number of hole carriers may be the Mott criterion, $n_c \approx 3 \times 10^{18} \text{ cm}^{-3}$, at $T_{tr}=340$ K on the general basis that an exponential decrease of the resistance with temperature in semiconductor physics indicates an exponential increase of carriers. Generally, in oxide materials, there are holes of about $5.5 \times 10^{18} \text{ cm}^{-3}$ which corresponds to 0.034% to d -band charges [17–19]. The holes are coupled to optical phonons [17]. In the metal regime above 340 K, the carriers are electrons (Fig. 1).

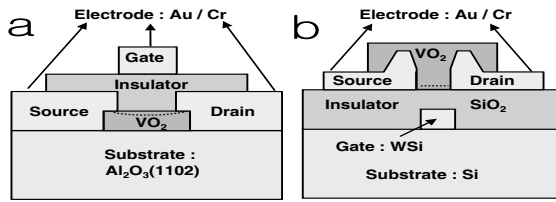


FIG. 2. Schematic diagram of transistors. The dotted line between VO₂ and insulator is a channel. The gate insulators are an amorphous Ba_{0.5}Sr_{0.5}TiO₃ for transistor 1 (Fig. a), and thermally treated amorphous SiO₂ for transistors 2 and 3 (Fig. b).

We fabricated transistors to observe the Mott transition. A schematic diagram of the transistors is shown in Fig. 2. Transistor 1 of a channel length, $L_{ch} = 3 \mu\text{m}$, and a gate width, $L_w = 50 \mu\text{m}$, was fabricated on Al₂O₃ substrates by lithography processes (Fig. 2a). A gate insulator of transistor 1 was an amorphous Ba_{0.5}Sr_{0.5}TiO₃ (BSTO) which was deposited on the VO₂ films. The interface between the VO₂ film and the amorphous gate insulator was sharp. A gate-source current, I_{GS} , between the gate and the source for transistor 1 is an order of 10^{-13} A, which indicates that there is sufficient insulation between the gate and the source. Transistors 2 and 3 of a gate length, $L_{ch} = 5 \mu\text{m}$, and a gate width, $L_w = 25 \mu\text{m}$, were manufactured on Si substrates. Their structure is shown in Fig. 2b. SiO₂ as the gate insulator was thermally treated. It is revealed that an interface between the polycrystal VO₂ film and the amorphous SiO₂ film is not sharp and complicated, and that the VO₂ films are inhomogeneous [20]. However, the SiO₂ insulator is strong with respect to a high field and is superior to the BSTO insulator for electronic application. Au/Cr electrodes were prepared for Ohmic contact. WSi is used as gate electrode. Characteristics of the transistors were measured by a precision semiconductor parameter ana-

lyzer (HP4156B). To protect transistors from excess current, the maximum current was limited to 20mA.

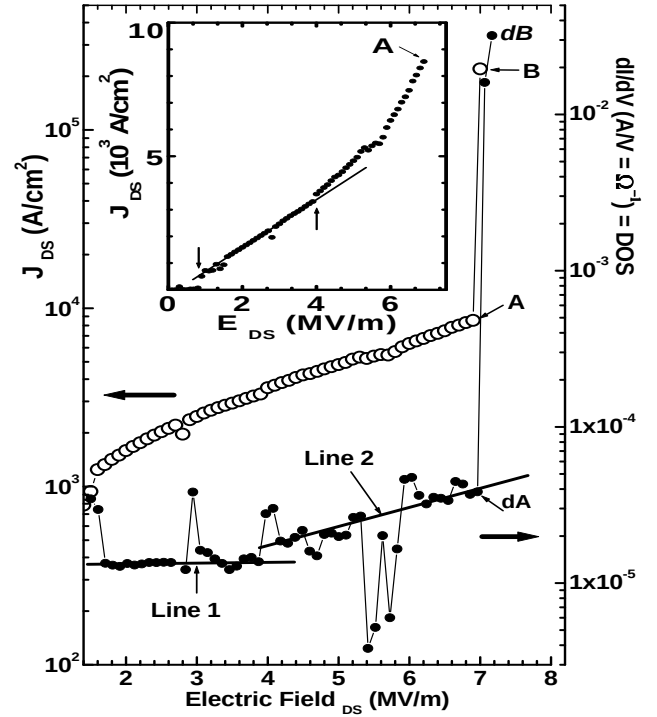


FIG. 3. Left-axis side: J_{DS} vs. E_{DS} for transistor 1. Right-axis side: Density of states (DOS), dI/dV , on the Fermi surface obtained from derivation with respect to V_{DS} . Inset: Ohmic behavior from $E_{DS}=0.8$ up to 4 MV/m is shown. The maximum current was limited to 20mA to protect the transistor.

Figure 3 shows the drain-source current density, J_{DS} , vs. the drain-source electric field, E_{DS} , for transistor 1, measured at $V_{gate}=0$ V (two-terminal structure). J_{DS} and E_{DS} are obtained from the drain-source current and the drain-source voltage, respectively; $I_{DS}=J_{DS}S_{DS}$ (S_{DS} : cross section) and $V_{DS} = E_{DS}L_{ch}$. J_{DS} behavior below point A (Inset of Fig. 3), as observed by Boriskov *et al.* [10] and Kumai *et al.* [8] who used an organic Mott-insulator, is linear from $E_{DS} \approx 0.8$ to 4 MV/m, but is nonlinear in the total regime. It was suggested that the linear Ohmic behavior occurs due to an applied field [10] and an induced current [8], not an increase of sample temperature due to leakage current. The Ohmic behavior was well described through a theoretical consideration in terms of a universal Landau-Zener quantum tunneling based on the Hubbard model [9]. However, since holes were observed below 334 K (Fig. 1b), it is asserted that the carriers for the Ohmic behavior are holes and the number of holes is very small. Thus, the Ohmic behavior is not an intrinsic property of metal and may be due to scattering of only a few carriers existing at room

temperature by a weak electric field because the density of states (DOS) does not depend on the electric field (line 1 in Fig. 3). Moreover, the nonlinear behavior is semi-conduction due to the increase of hole carriers by Zener's impact ionization and is a doping process wherein n_c of holes are induced by the electric field. This is supported by the fact that the DOS increases exponentially with an increasing electric field (line 2 of Fig. 3). Thus, the VO_2 film below point A is regarded as a semiconductor.

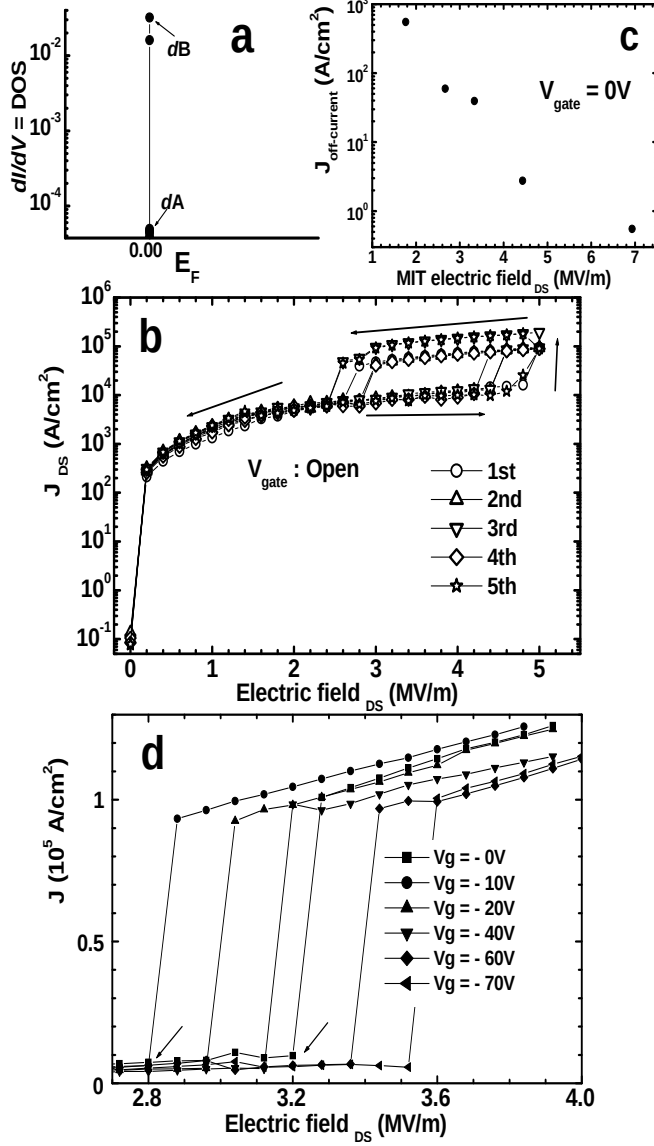


FIG. 4. **a**, DOSs in Fig.3 are redrawn with respect to the Fermi level. E_F denotes the Fermi level. **b**, Hysteresis loops measured in transistor 2. Measurements of 5 times were continuously carried out. **c**, Off-current vs. MIT- E_{DS} . The off-currents (or leakage current) were extracted from 5 transistors. **d**, J_{DS} vs. E_{DS} near the abrupt jump of transistor 3. MIT electric field increases with increasing negative gate voltage from $V_g = -10V$. Above $J_{DS} \approx 0.9 \times 10^5$ A/cm², Ohmic behavior is exhibited.

Abrupt jumps of J_{DS} at point A and the DOS at point dA are shown in Fig. 3. The measured maximum-current density at point B is $J_{measured} \approx 2 \times 10^5$ A/cm², which is an order of the current density observable in a dirty metal. Note that the true maximum current density is much higher than $J_{measured}$, because the measurement was limited to 20mA. The jump of J_{DS} between point A and point B corresponds to a jump of conductivity, σ , because J_{DS} is $\sigma E = n_{free} e v$ and E is constant between points A and B; $\sigma \propto n_{free}$, where n_{free} is the number of electron carriers (above point A) on the Fermi surface, and v is the carrier velocity on the Fermi surface and is constant between points A and B due to constant E . This indicates that the number of carriers discontinuously increases, and that the DOS on the Fermi surface jumps from points dA to dB (Fig. 3). The jump of the DOS is a typical behavior of a first-order MIT which was first theoretically derived by Brinkman and Rice [6]. Note that carriers for current measured in semiconductors and metals are on the Fermi surface. Derivatives, dI/dV , at respective fields correspond to the DOSs on the Fermi surface (Fig. 3). The DOS in Fig. 3 can be expressed in terms of the Fermi level (Fig. 4a). Moreover, hysteresis loops of 5 times for transistor 2 were continuously measured (Fig. 4b), which may be due to the Joule heating and is also evidence of a first-order MIT. The abrupt jump was also measured more than 1,500 times without breakdown in a transistor. Fig. 4d shows Ohmic behavior after jump, which indicates that this phase is metal. Thus, we suggest that the jump at point A is the abrupt MIT (or Mott transition). If Hubbard's continuous MIT exists, the jump should be not observed and the nonlinear behavior with an increasing field in the inset of Fig. 3 should be continuously exhibited from point A to point B in the electron system. However, continuous behavior is not found.

Figure 4c shows the off-current density, $J_{off-current}$, vs. the MIT drain-source electric field, MIT- E_{DS} , at $V_{gate} = 0V$ (two-terminal structure). Although $V_{gate} = 0V$, the gate-source currents were very small to be ignored. The off-current is defined as I_{DS} near $V_{DS} = 0V$ and $V_g = 0V$ (or gate open); other researchers refer to off-current as leakage-current. Data were selected from 5 transistors. MIT- E_{DS} increases with decreasing $J_{off-current}$, which also provides information for revealing the mechanism of the abrupt jump. The off-current is caused by the excitation of holes in impurity levels such as oxygen deficiency. When the number of total holes in the hole levels is given by $n_{tot} = n_b + n_{free}$, where n_b is the number of bound holes in the levels and n_{free} is the number of holes freed from the levels. n_b decreases with increasing n_{free} , because n_{tot} is constant. The larger off-current is attributed to the increase of n_{free} . For the abrupt jump, $\Delta n \equiv n_c - n_{free} = 0$ should be satisfied, where $n_c \approx 3 \times 10^{18} \text{ cm}^{-3}$, as predicted by Mott. Hence, the decrease of Δn (increase of n_{free}) contributes to the

reduction of the MIT- E_{DS} .

Figure 4d shows J_{DS} vs. E_{DS} near the abrupt jump of transistor 3. Its characteristics are as follows. First, the gate effect at $E_{DS}=2.8\text{MV/m}$ and $V_{gate}=-10\text{V}$ is due to induced holes and occurs suddenly; this indicates attainment of n_c . Second, the MIT- E_{DS} increases with increasing negative gate voltage (or field), which is due to a decrease of the conductivity; J_{DS} at MIT points can be nearly regarded as constant and $\sigma_{DS} = J_{DS}/E_{DS}$. This is due to an increase of hole carriers generated by the negative gate fields and indicates an increase of inhomogeneity (injection of holes to electron system). It was also observed that the MIT- E_{DS} decreases with increasing positive gate voltage when the off-current is large. Third, in the metal (electron system) regime over $J_{DS}=0.9\times 10^4\text{ mA/cm}^2$, Ohmic behavior differs from the Ohmic behavior in the hole system in Fig. 3 and arises from a dirty interface between the polycrystal VO_2 film and the amorphous SiO_2 . The dirty interface causes resistance [20] and is a channel where current flows (Fig. 2b). We suggest that the Ohmic behavior in Fig. 4d is a true metallic characteristic. Finally, the gate induced abrupt MIT reveals that the MIT depends upon the hole carriers in the semiconductor regime, and that inhomogeneity also inevitably arises from hole doping [21].

In conclusion, in the Mott insulator of VO_2 , MIT near $U/U_c=1$ abruptly occurs in company with inhomogeneity through semiconduction as a doping process of internal holes of $n_c\approx 0.018\%$. This will be observed in all Mott insulators.

We thank Dr. Soo-Hyeon Park at KBSI for Hall-effect measurement, Dr. Gyungock Kim for valuable discussions on the Zener transition, and Dr. J. H. Park for fabrication of Si_3N_4 films with CVD. HT Kim, the leader of this project, developed the concept, and wrote the paper. BG Chae and DH Youn deposited VO_2 and BSTO films, performed the transistor fabrication process including Si based transistors, and measured $I - V$ characteristics. KY Kang prepared the laser-ablation and lithography equipments and generated this project with HT Kim. SL Maeng evaluated transistor characteristics, the shielding measurement system, and the Si_3N_4 film fabrication.

- ⁵ F. J. Morin, Phys. Rev. Lett. 3, 34 (1959).
- ⁶ W. F. Brinkman, T. M. Rice, Phys. Rev. B2, 4302 (1970).
- ⁷ J. Hubbard, *ibid* 281, 401 (1965).
- ⁸ R. Kumai, Y. Okimoto, and Y. Tokura, Science 284, 1645 (1999).
- ⁹ T. Oka, R. Arita, and H. Aoki, cond-mat/0304036.
- ¹⁰ P. P. Boriskov, A. A. Velichko, A. L. Pergament, G. B. Stefanovich, and D. G. Stefanovich, Techni. Phys. Lett. 28, 406 (2002).
- ¹¹ S. M. Sze, *Physics of Semiconductor Devices* Chapter 7, (John Wiley and Sons, 1981).
- ¹² G. Stefanovich, A. Pergament, and D. Stefanovich, J. Phys.: Condens. Matter 12, 8837 (2000).
- ¹³ T. M. Rice, H. Launois, and J. P. Pouget, Phys. Rev. Lett. 73, 3042 (1994).
- ¹⁴ R. Zimmermann, R. Claessen, F. Reinert, P. Steiner, and S. Hüfner, J. Phys.: Condens. Matter 10, 5697 (1998).
- ¹⁵ J. F. De Natale, P. J. Hood, and A. B. Harker, J. Appl. Phys. 66, 5844 (1989).
- ¹⁶ M. Borek, F. Qian, V. Nagabushnam, and R. K. Singh, Appl. Phys. Lett. 63, 3288 (1993).
- ¹⁷ H. T. Kim, H. Minami, and H. Uwe, *Advances in Superconductivity VII* (Springer-Verlag Press, 1995) p. 169; cond-mat/0303442.
- ¹⁸ I. L. Botto, M. B. Vassallo, E. J. Baran, and G. Minelli, Mater. Chem. Phys. 50, 267 (1997).
- ¹⁹ K. Segal, H. Kasai, and H. Sakata, Mater. Chem. Phys. 53, 28 (1998).
- ²⁰ D. H. Youn, B. G. Chae, H. T. Kim, J. W. Lee, and K. Y. Kang, unpublished.
- ²¹ H. T. Kim, *New Trends in Superconductivity* (Kluwer Press, 2002), NATO Science Series Vol. II/67, p. 137; cond-mat/0110112.

* htkim@etri.re.kr, kimht45@hotmail.com

¹ N. F. Mott *Metal - Insulator Transition* (Taylor and Frances Press, 1990).

² X. Y. Zhang, M. J. Rozenberg, and G. Kotliar, Phys. Rev. Lett. 70, 1666 (1993).

³ M. Imada, A. Fujimori, and Y. Tokura, Rev. Mod. Phys. 70, 1039 (1998).

⁴ P. Fazekas *Lecture Notes on Electron Correlation and Magnetism* (World Scientific Press, 1999).